

## 40V N-Channel MOSFETs

### General Description

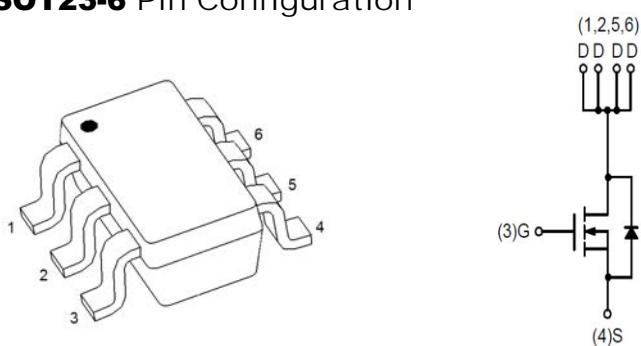
These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

$BV_{DSS}$	$R_{DS(ON)}\text{Typ.}$	$I_D$
40V	17mΩ	8A

### Features

- 40V, 8A,  $R_{DS(ON)}\text{Typ.}=17m\Omega$  @  $V_{GS} = 10V$
- Improved dv/dt capability
- Fast switching
- Green Device Available

### SOT23-6 Pin Configuration



### Absolute Maximum Ratings $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	40	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$	Drain Current – Continuous ( $T_c=25^\circ\text{C}$ ) (Chip Limitation)	8	A
	Drain Current – Continuous ( $T_c=100^\circ\text{C}$ ) (Chip Limitation)	5	A
$I_{DM}$	Drain Current – Pulsed <sup>1</sup>	32	A
$E_{AS}$	Single Pulse Avalanche Energy <sup>2</sup>	31	mJ
$I_{AS}$	Single Pulse Avalanche Current <sup>2</sup>	25	A
$P_D$	Power Dissipation ( $T_c=25^\circ\text{C}$ )	1.2	W
$T_{STG}$	Storage Temperature Range	-50 to 150	$^\circ\text{C}$
$T_J$	Operating Junction Temperature Range	-50 to 150	$^\circ\text{C}$

Note 1: Exceed these limits to damage to the device.

Note 2: Exposure to absolute maximum rating conditions may affect device reliability.

**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**
**Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_{\text{D}}=250\mu\text{A}$	40			V
$I_{\text{DSS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=40\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$			1	$\mu\text{A}$
		$V_{\text{DS}}=32\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=125^\circ\text{C}$			10	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$ , $V_{\text{DS}}=0\text{V}$			$\pm 100$	$\text{nA}$

**On Characteristics**

$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance	$V_{\text{GS}}=10\text{V}$ , $I_{\text{D}}=7\text{A}$		17	22	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}$ , $I_{\text{D}}=6\text{A}$		22	26	$\text{m}\Omega$
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$ , $I_{\text{D}}=250\mu\text{A}$	1.0	1.6	2.5	V
$\Delta V_{\text{GS(th)}}$	$V_{\text{GS(th)}}$ Temperature Coefficient			-5		$\text{mV/C}$
$g_{\text{fs}}$	Forward Transconductance	$V_{\text{DS}}=5\text{V}$ , $I_{\text{D}}=4\text{A}$		33		S

**Dynamic and switching Characteristics**

$Q_g$	Total Gate Charge <sup>3,4</sup>	$V_{\text{DS}}=32\text{V}$ , $V_{\text{GS}}=4.5\text{V}$ , $I_{\text{D}}=7\text{A}$		9.8		nC
$Q_{\text{gs}}$	Gate-Source Charge <sup>3,4</sup>			2.8		
$Q_{\text{gd}}$	Gate-Drain Charge <sup>3,4</sup>			3.9		
$T_{\text{d(on)}}$	Turn-On Delay Time <sup>3,4</sup>	$V_{\text{DD}}=20\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $R_{\text{G}}=3.3\Omega$ $I_{\text{D}}=7\text{A}$		2.8		ns
$T_r$	Rise Time <sup>3,4</sup>			40.4		
$T_{\text{d(off)}}$	Turn-Off Delay Time <sup>3,4</sup>			22.8		
$T_f$	Fall Time <sup>3,4</sup>			6.4		
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=15\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $F=1\text{MHz}$		1013		pF
$C_{\text{oss}}$	Output Capacitance			107		
$C_{\text{rss}}$	Reverse Transfer Capacitance			76		
$R_g$	Gate resistance	$V_{\text{GS}}=0\text{V}$ , $V_{\text{DS}}=0\text{V}$ , $F=1\text{MHz}$		1.2		$\Omega$

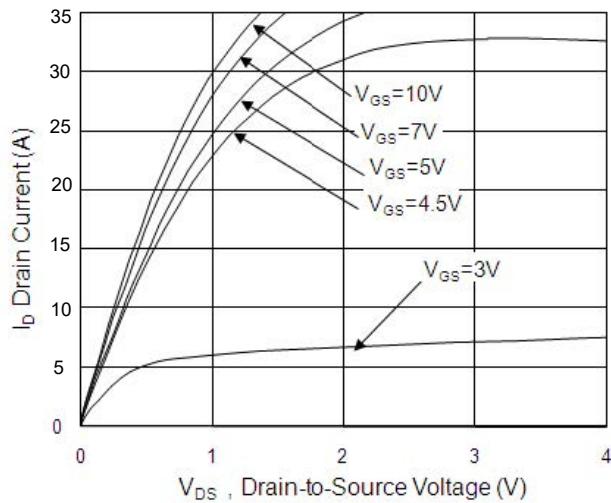
**Drain-Source Diode Characteristics and Maximum Ratings**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current	$V_G=V_D=0\text{V}$ , Force Current			8	A
$I_{\text{SM}}$	Pulsed Source Current				16	A
$V_{\text{SD}}$	Diode Forward Voltage	$V_{\text{GS}}=0\text{V}$ , $I_s=1\text{A}$ , $T_J=25^\circ\text{C}$			1	V

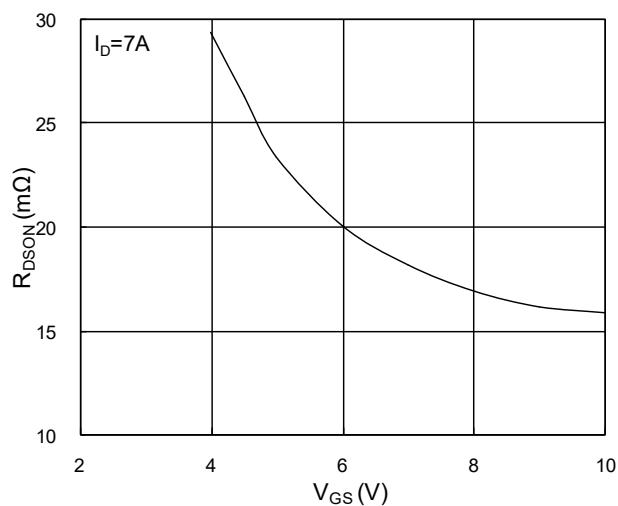
Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2.  $V_{\text{DD}}=25\text{V}$ ,  $V_{\text{GS}}=10\text{V}$ ,  $L=0.1\text{mH}$ ,  $I_{\text{AS}}=85\text{A}$ , Starting  $T_J=25^\circ\text{C}$
3. The data tested by pulsed , pulse width  $\leq 300\text{us}$  , duty cycle  $\leq 2\%$ .
4. Essentially independent of operating temperature.

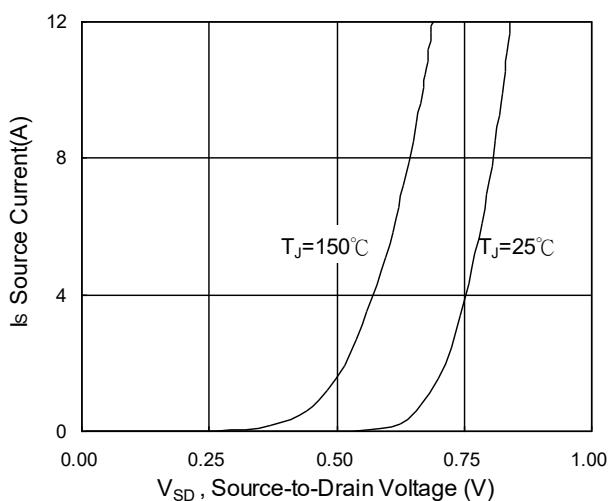
## Typical Characteristics



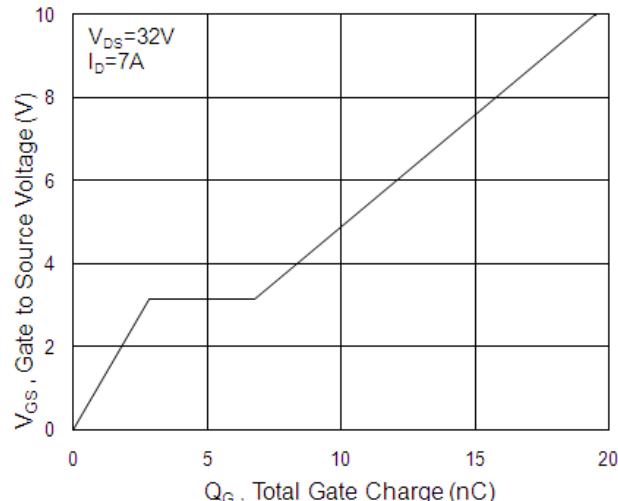
**Fig.1 Typical Output Characteristics**



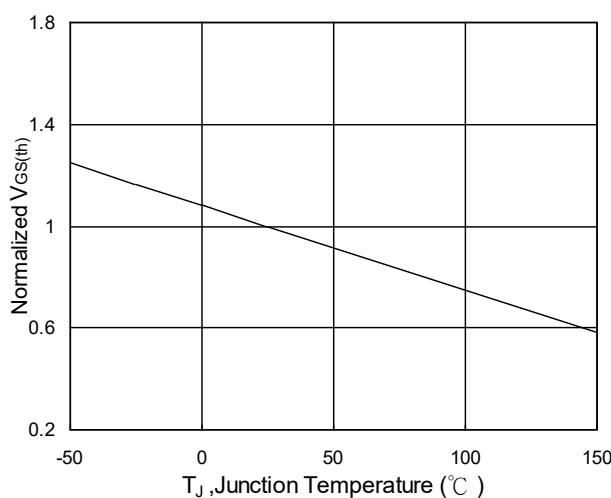
**Fig.2 On-Resistance vs. G-S Voltage**



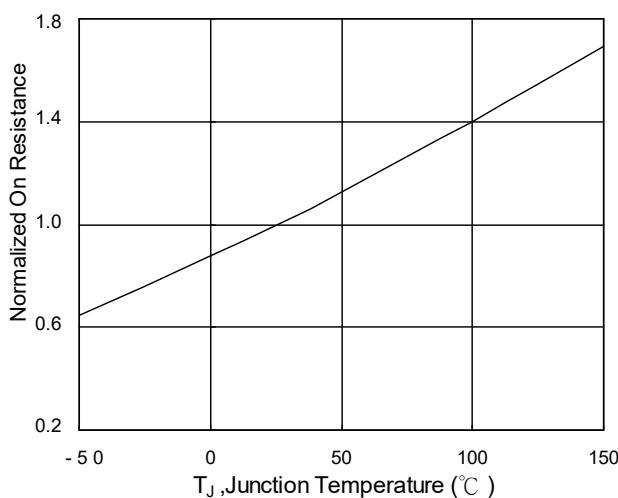
**Fig.3 Forward Characteristics of Reverse**



**Fig.4 Gate-Charge Characteristics**

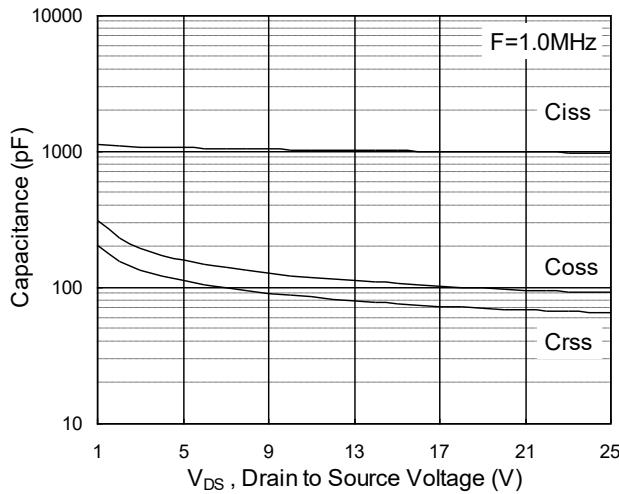


**Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$**

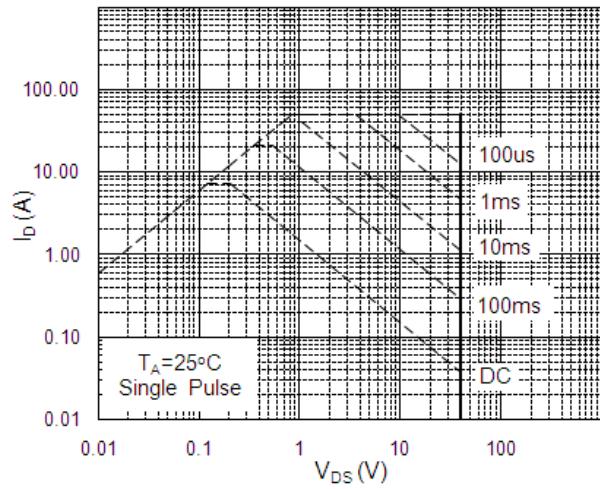


**Fig.6 Normalized  $R_{DS(on)}$  vs.  $T_J$**

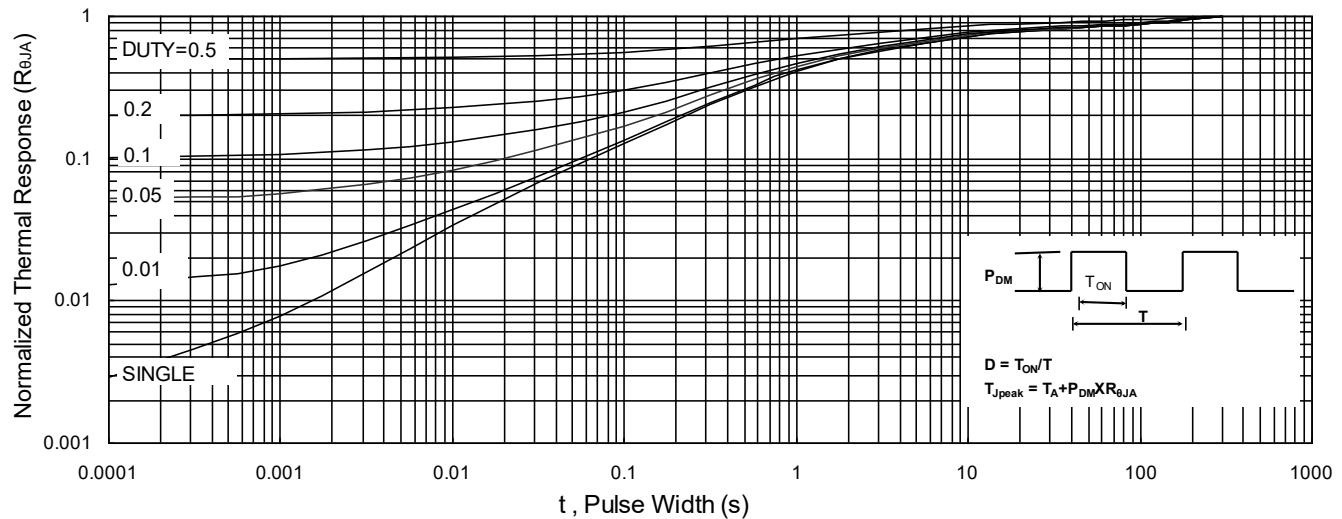
## Typical Characteristics



**Fig.7 Capacitance**

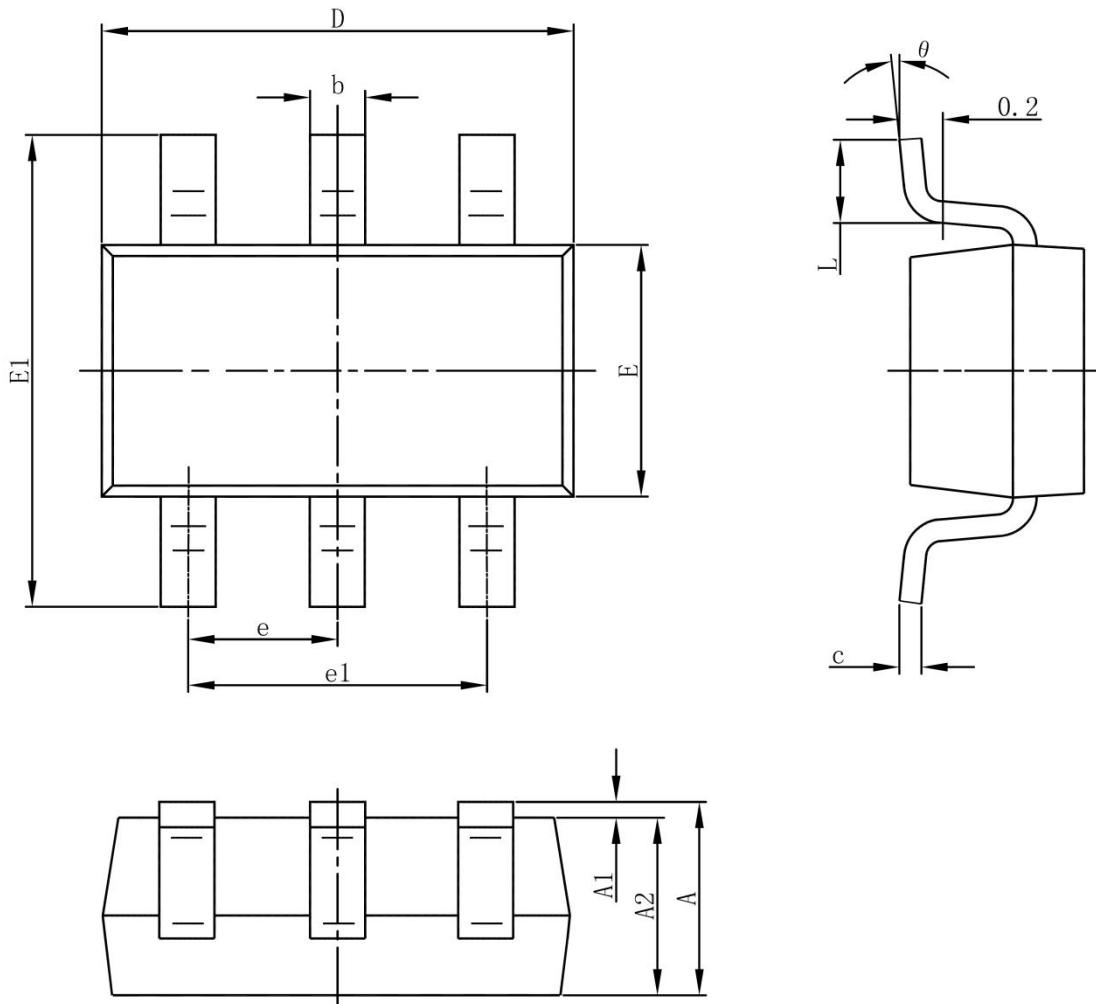


**Fig.8 Safe Operating Area**



**Fig.9 Normalized Maximum Transient Thermal Impedance**

### SOT23-6 Package Outline Dimensions



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°

V 1.0